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a!

support guides 36a, 36b, is shaped having an arcuate configuration such that, when the wafer 32 and wafer boat 30 are subjected to wafer processing temperatures of about 1000 °C and above, the shape of the supporting grooved portion 38 will substantially correspond to the shape of the part of the wafer 32 contacting the supporting grooved portion 38, thereby supporting the wafer 32 across the entire arcuate portion of a circular wafer's periphery which is in contact with the supporting grooved portion. In other words, the lower arcuate periphery of the circular wafer rests upon and is supported by the supporting grooved portion 38 when the wafer 32 is positioned in a slot 34 in wafer boat 30 and maintained in a vertical position by the upper support guides 36a, 36b. The wafer boat 30 having this configuration provides exceptional support for and stabilization of the wafers 32 positioned in the slots 34. Additionally, the wafer boat 30 of the present invention includes one or more large openings or windows 40 between each end of the boat in order to increase the radiation view factors and decrease radiation blocking caused by the boat, as compared to boats currently known in the art.

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Please replace the paragraph beginning at page 11, line 19 and extending to page 12, line 2, with the following rewritten paragraph:

Q2

--[Since they are formed of different materials, the wafer 32 and the wafer boat 30 have different thermal expansion coefficients. In one embodiment, the wafer boats of the present invention are formed of SiC. One preferred SiC comprises recrystallized SiC commercially available from Saint-Gobain Industrial Ceramics Inc., of Worcester, Massachusetts under the tradename CRYSTAR®. Such materials can comprise either recrystallized SiC or silicon impregnated SiC where semiconductor grade silicon has been used to fill porosity in the body. The silicon impregnated material can be further provided with a layer of CVD-SiC to seal the surface and prevent silicon migration during use of the device in wafer processing.]--

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***In the claims:***

Please cancel ~~claims~~ 9-13.

Please amend claim 1 as follows: